

-100 Volt, 0.30Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

Product Summary

| Part Number | BV _{DSS} | R _{DSON} | I _D |
|--------------|-------------------|-------------------|----------------|
| JANTX2N6804 | -100V | 0.30Ω | -11A |
| JANTXV2N6804 | | | |

Features:

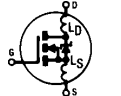
- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed

Absolute Maximum Ratings

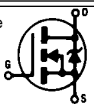
| | Parameter | JANTX2N6804, JANTXV2N6804 | Units |
|---|---------------------------------|--|-------|
| I _D @ V _{GS} = -10V, T _C = 25°C | Continuous Drain Current | -11 | A |
| I _D @ V _{GS} = -10V, T _C = 100°C | Continuous Drain Current | -7 | |
| I _{DM} | Pulsed Drain Current ① | -50 | |
| P _D @ T _C = 25°C | Max. Power Dissipation | 75 | W |
| | Linear Derating Factor | 0.60 | W/K ⑤ |
| V _{GS} | Gate-to-Source Voltage | ±20 | V |
| E _{AS} | Single Pulse Avalanche Energy ② | 81 | mJ |
| I _{AR} | Avalanche Current ① | -11 | A |
| E _{AR} | Repetitive Avalanche Energy ① | 7.5 | mJ |
| dv/dt | Peak Diode Recovery dv/dt ③ | -5.5 | V/ns |
| T _J | Operating Junction | -55 to 150 | °C |
| T _{STG} | Storage Temperature Range | | |
| | Lead Temperature | 300 (0.063 in. (1.6mm) from case for 10.5 seconds) | |
| | Weight | 11.5 (typical) | |

JANTX2N6804, JANTXV2N6804 Device

Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

| | Parameter | Min. | Typ. | Max. | Units | Test Conditions |
|------------------------------|--|------|--------|------|----------|--|
| BV_{DSS} | Drain-to-Source Breakdown Voltage | -100 | — | — | V | $V_{GS} = 0V, I_D = -1.0 \text{ mA}$ |
| $\Delta BV_{DSS}/\Delta T_J$ | Temperature Coefficient of Breakdown Voltage | — | -0.087 | — | V/°C | Reference to 25°C, $I_D = -1.0 \text{ mA}$ |
| RDS(on) | Static Drain-to-Source | — | — | 0.30 | Ω | $V_{GS} = -10V, I_D = -7A$ ④ |
| | On-State Resistance | — | — | 0.35 | | $V_{GS} = -10V, I_D = -11A$ |
| $V_{GS(th)}$ | Gate Threshold Voltage | -2.0 | — | -4.0 | V | $V_{DS} = V_{GS}, I_D = -250\mu A$ |
| g_{fs} | Forward Transconductance | 3 | — | — | S (r) | $V_{DS} > -15V, I_{DS} = -7A$ ④ |
| IDSS | Zero Gate Voltage Drain Current | — | — | -25 | μA | $V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0V$ |
| | | — | — | -250 | | $V_{DS} = 0.8 \times \text{Max Rating}$ $V_{GS} = 0V, T_J = 125^\circ C$ |
| IGSS | Gate-to-Source Leakage Forward | — | — | -100 | nA | $V_{GS} = -20V$ |
| IGSS | Gate-to-Source Leakage Reverse | — | — | 100 | nA | $V_{GS} = 20V$ |
| Qg | Total Gate Charge | 1.5 | — | 29 | nC | $V_{GS} = -10V, I_D = -11A$ $V_{DS} = \text{Max. Rating} \times 0.5$ see figures 6 and 13 |
| Qgs | Gate-to-Source Charge | 1.0 | — | 7.1 | | |
| Qgd | Gate-to-Drain ("Miller") Charge | 2.0 | — | 21 | | |
| td(on) | Turn-On Delay Time | — | — | 60 | ns | $V_{DD} = -50V, I_D = -11A,$ $R_G = 7.5\Omega, V_{GS} = -10V$ see figure 10 |
| tr | Rise Time | — | — | 140 | | |
| td(off) | Turn-Off Delay Time | — | — | 140 | | |
| tf | Fall Time | — | — | 140 | | |
| LD | Internal Drain Inductance | — | 5.0 | — | nH | <p>Measured from the drain lead, 6mm (0.25 in.) from package to center of die.</p> <p>Modified MOSFET symbol showing the internal inductances.</p>  |
| LS | Internal Source Inductance | — | 13 | — | | |
| Ciss | Input Capacitance | — | 860 | — | pF | $V_{GS} = 0V, V_{DS} = -25V$ $f = 1.0 \text{ MHz}$ see figure 5 |
| Coss | Output Capacitance | — | 350 | — | | |
| Crss | Reverse Transfer Capacitance | — | 125 | — | | |

Source-Drain Diode Ratings and Characteristics

| | Parameter | Min. | Typ. | Max. | Units | Test Conditions |
|-----|--|---|------|------|---------|--|
| IS | Continuous Source Current (Body Diode) | — | — | -11 | A | <p>Modified MOSFET symbol showing the integral reverse p-n junction rectifier.</p>  |
| ISM | Pulse Source Current (Body Diode) ① | — | — | -50 | | |
| VSD | Diode Forward Voltage | — | — | -4.7 | V | $T_J = 25^\circ C, I_S = -11A, V_{GS} = 0V$ ④ |
| trr | Reverse Recovery Time | — | — | 250 | ns | $T_J = 25^\circ C, I_F = -11A, di/dt \leq -100A/\mu s$ $V_{DD} \leq -50V$ ④ |
| QRR | Reverse Recovery Charge | — | — | 3.0 | μC | |
| ton | Forward Turn-On Time | Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by LS + LD. | | | | |

Thermal Resistance

| | Parameter | Min. | Typ. | Max. | Units | Test Conditions |
|-------|---------------------|------|------|------|-------|----------------------|
| RthJC | Junction-to-Case | — | — | 1.67 | K/W | Typical socket mount |
| RthJA | Junction-to-Ambient | — | — | 30 | | |

JANTX2N6804, JANTXV2N6804 Device

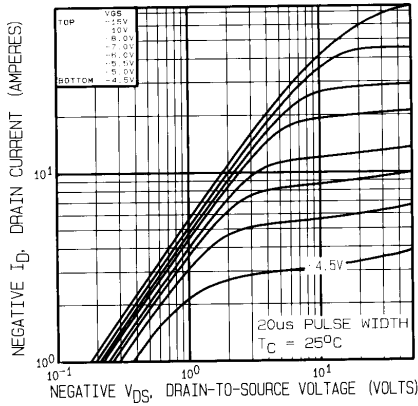


Fig. 1 — Typical Output Characteristics
 $T_C = 25^\circ\text{C}$

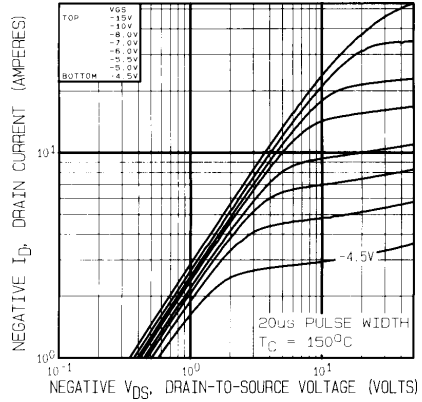


Fig. 2 — Typical Output Characteristics
 $T_C = 150^\circ\text{C}$

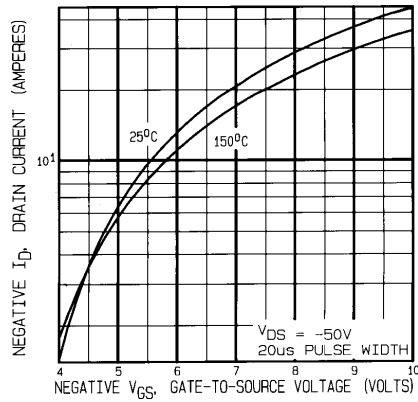


Fig. 3 — Typical Transfer Characteristics

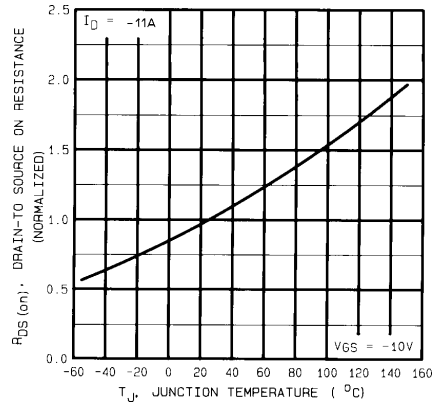


Fig. 4 — Normalized On-Resistance Vs. Temperature

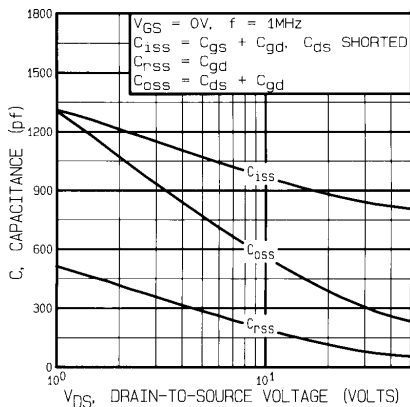


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

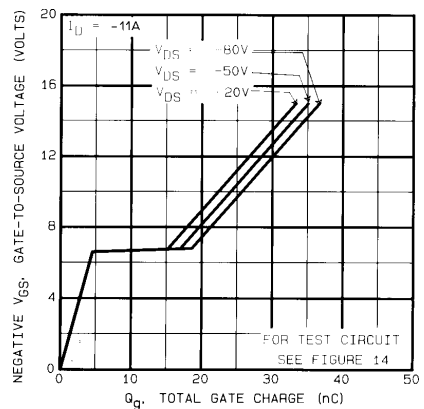


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

JANTX2N6804, JANTXV2N6804 Device

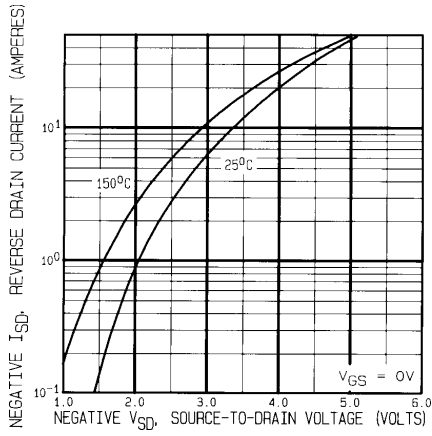


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

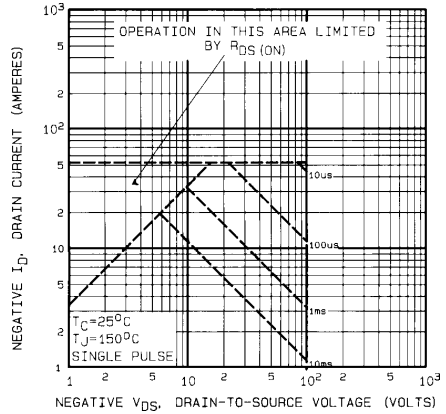


Fig. 8 — Maximum Safe Operating Area

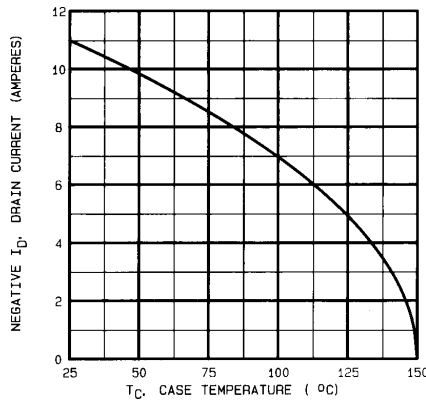


Fig. 9 — Maximum Drain Current Vs. Case Temperature

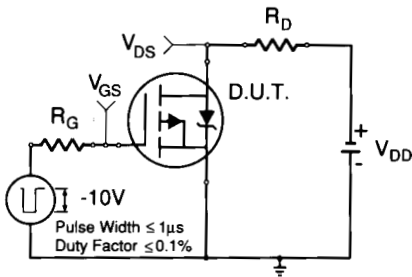


Fig. 10a — Switching Time Test Circuit

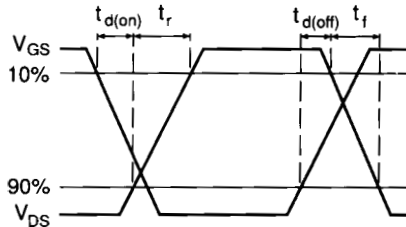


Fig. 10b — Switching Time Waveforms

JANTX2N6804, JANTXV2N6804 Device

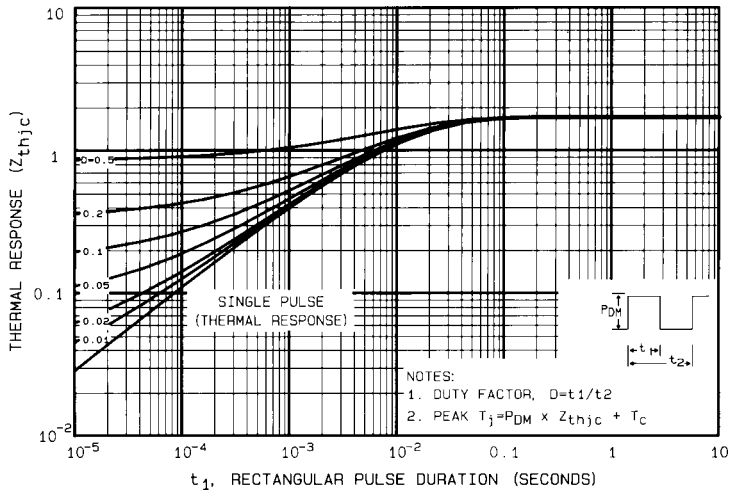


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

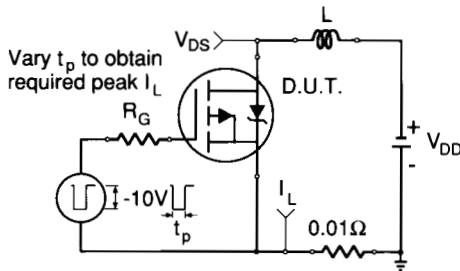


Fig. 12a — Unclamped Inductive Test Circuit

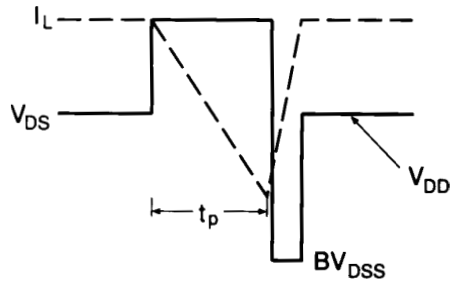


Fig. 12b — Unclamped Inductive Waveforms

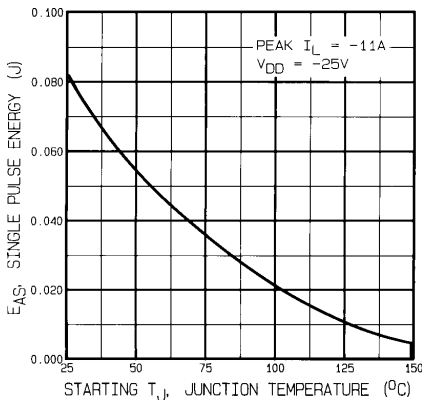


Fig. 12c — Max. Avalanche Energy vs. Current

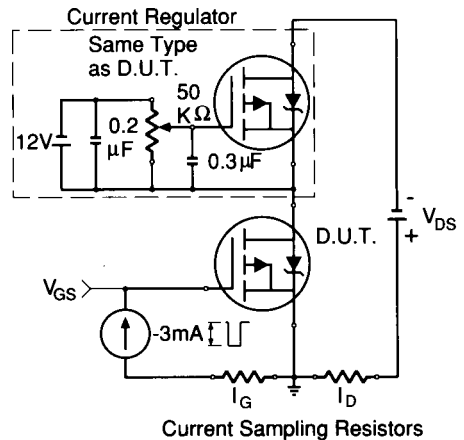


Fig. 13a — Gate Charge Test Circuit

JANTX2N6804, JANTXV2N6804 Device

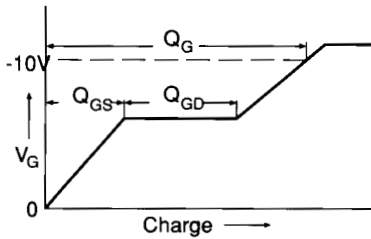
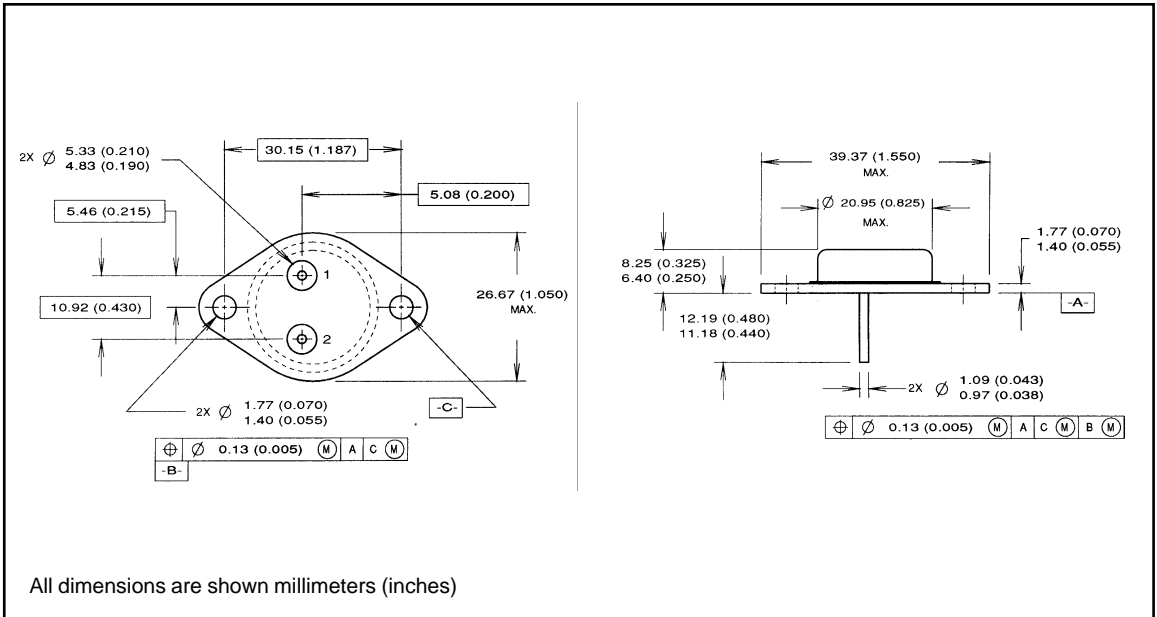


Fig. 13b — Basic Gate Charge Waveform

- ① Repetitive Rating; Pulse width limited by maximum junction temperature. (see figure 11)
- ② @ $V_{DD} = -25V$, Starting $T_J = 25^\circ C$,
 $E_{AS} = [0.5 * L * (I_L^2) * [BV_{DSS}/(BV_{DSS}-V_{DD})]$
 Peak $I_L = -11A$, $V_{GS} = -10V$, $25 \leq R_G \leq 200\Omega$
- ③ $I_{SD} \leq -11A$, $di/dt \leq -140A/\mu s$,
 $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^\circ C$
- ④ Pulse width $\leq 300 \mu s$; Duty Cycle $\leq 2\%$
- ⑤ $K/W = ^\circ C/W$
 $W/K = W/^\circ C$

Case Outline and Dimensions — TO-204AA (Modified TO-3)



International
IR Rectifier

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331

EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020

IR CANADA: 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897

IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

IR FAR EAST: K&H Bldg., 2F, 3-30-4 Nishi-Ikeburo 3-Chome, Toshima-Ki, Tokyo Japan 171 Tel: 81 3 3983 0086

IR SOUTHEAST ASIA: 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371

<http://www.irf.com/>

Data and specifications subject to change without notice.

10/96